

ABSTRACT

A composite sheet for forming a protective film, the composite sheet including a substrate, an adhesive layer having active energy ray curability, and a film for forming a protective film having heat curability, wherein

this composite sheet for forming a protective film is used for producing semiconductor chips with a protective film by affixing the composite sheet to the back surface of a semiconductor wafer via the film for forming a protective film, and then converting the film for forming a protective film to a protective film, subsequently dicing the semiconductor wafer to produce semiconductor chips, curing the adhesive layer, and then picking up the semiconductor chips together with the protective film,

the adhesive layer contains, at least in the layer that contacts the film for forming a protective film, an alkyl (meth)acrylate ester copolymer, and

this copolymer has a structural unit derived from an alkyl (meth)acrylate ester in which the carbon number of the alkyl group that constitutes the alkyl ester is 8 or greater.